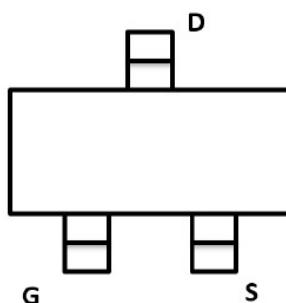
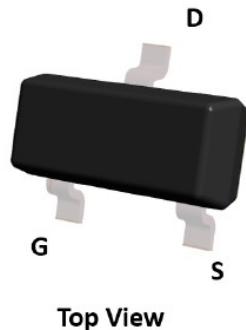
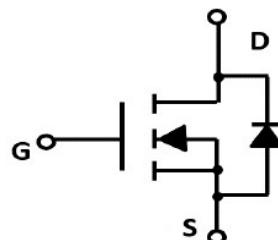


N-Channel Enhancement Mode Field Effect Transistor



SOT-23



Product Summary

- V_{DS} 40V
- I_D 5.0A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) < 45mohm
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) < 60mohm
- 100% V_{DS} Tested

General Description

- Trench Power LV MOSFET technology
- High Power and current handling capability
- AEC-Q101 qualified

Applications

- PWM application
- Load switch

Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	40	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	$T_A=25^\circ C$	I_D	5	A
	$T_A=70^\circ C$		4	
Pulsed Drain Current ^A		I_{DM}	20	A
Total Power Dissipation	$T_A=25^\circ C$	P_D	1.2	W
	$T_A=70^\circ C$		0.8	W
Thermal Resistance Junction-to-Ambient ^B		$R_{\Theta JA}$	104	$^\circ C/W$
Junction and Storage Temperature Range		T_J, T_{STG}	-55 ~ +150	$^\circ C$

Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
FTK05N04C	F2	05N04C.	3000	30000	120000	7" reel



FTK05N04C

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$			1	μA
Gate-Body Leakage Current	I_{GSS1}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
	I_{GSS2}	$V_{\text{GS}}=\pm 10\text{V}, V_{\text{DS}}=0\text{V}$			± 50	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.5	2.5	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=5\text{A}$		30	45	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=3\text{A}$		40	60	
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=5\text{A}, V_{\text{GS}}=0\text{V}$			1.2	V
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		417		pF
Output Capacitance	C_{oss}			73		
Reverse Transfer Capacitance	C_{rss}			59		
Switching Parameters						
Total Gate Charge	Q_{g}	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=20\text{V}, I_{\text{D}}=3.5\text{A}$		9.76		nC
Gate-Source Charge	Q_{gs}			1.85		
Gate-Drain Charge	Q_{gd}			2.14		
Reverse Recovery Charge	Q_{rr}	$I_{\text{F}}=3.5\text{A}, \frac{dI}{dt}=100\text{A/us}$		2.6		ns
Reverse Recovery Time	t_{rr}			19.1		
Turn-on Delay Time	$t_{\text{D(on)}}$			4.4		
Turn-on Rise Time	t_{r}	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=20\text{V}, I_{\text{D}}=3.5\text{A}$ $R_{\text{GEN}}=3\Omega$		21		ns
Turn-off Delay Time	$t_{\text{D(off)}}$			12		
Turn-off fall Time	t_{f}			19.6		

A. Pulse Test: Pulse Width $\leq 300\text{us}$, Duty cycle $\leq 2\%$.

B. R_{eJA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{eJC} is guaranteed by design, while R_{eJA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.

■ Typical Performance Characteristics

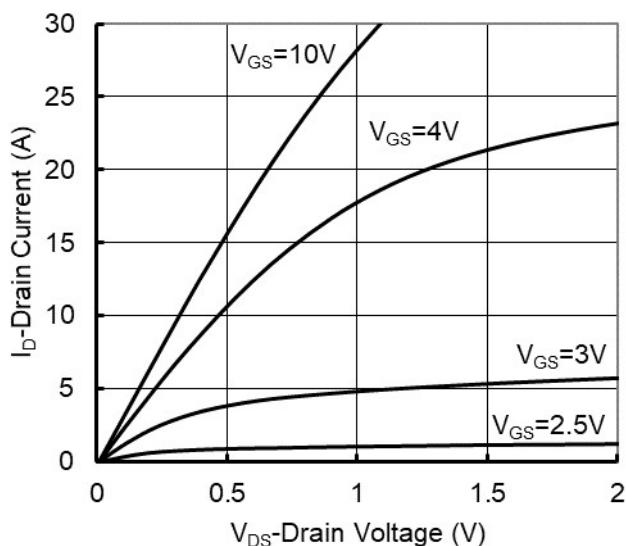


Figure 1. Output Characteristics

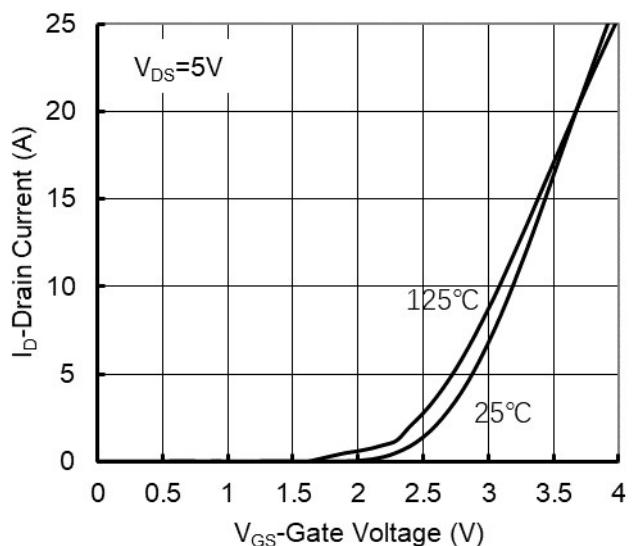


Figure 2. Transfer Characteristics

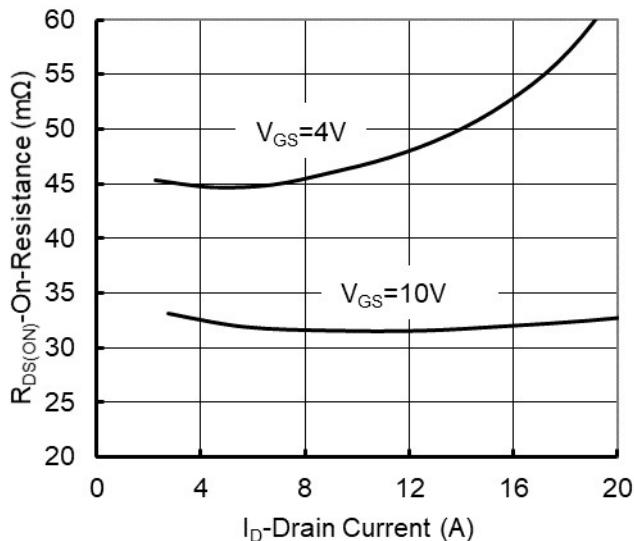


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

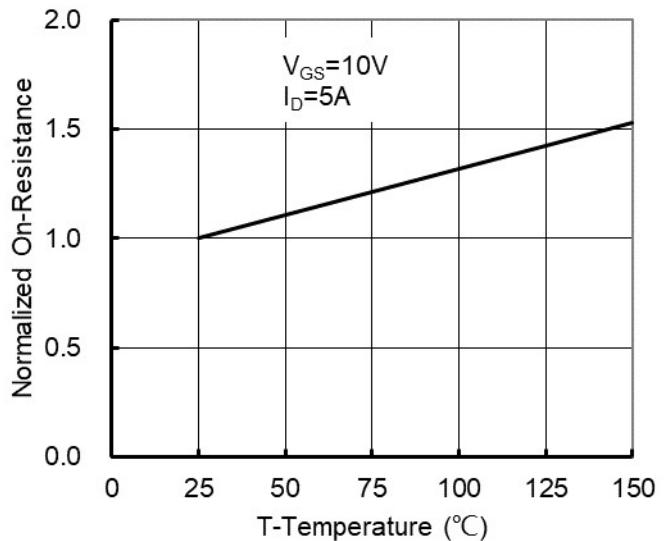


Figure 4: On-Resistance vs. Junction Temperature

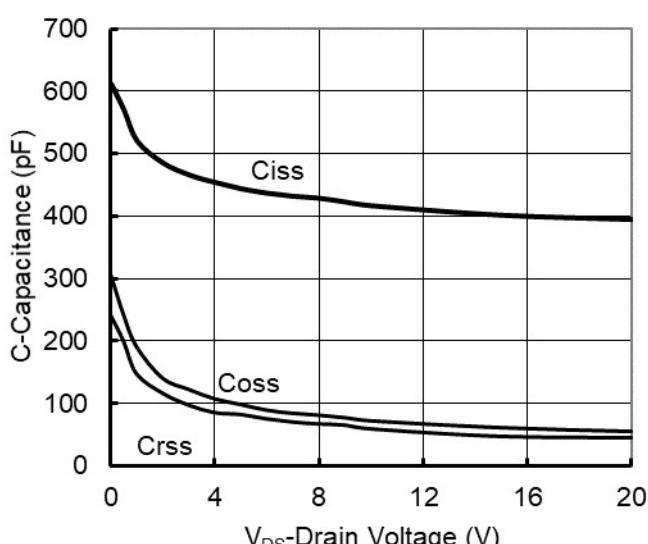


Figure 5. Capacitance Characteristics

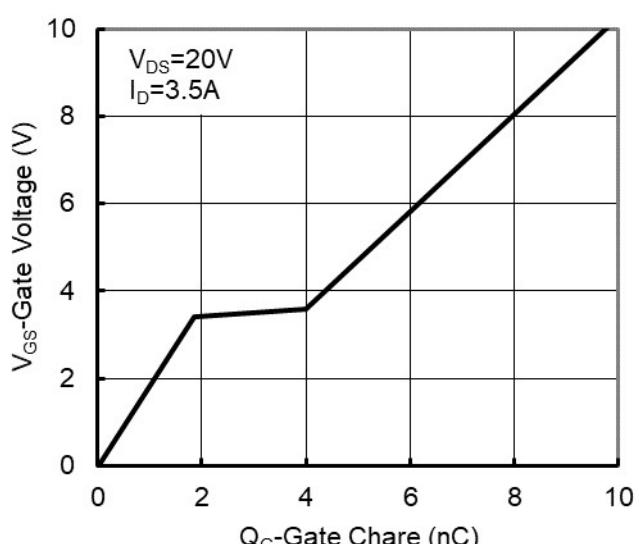


Figure 6. Gate Charge

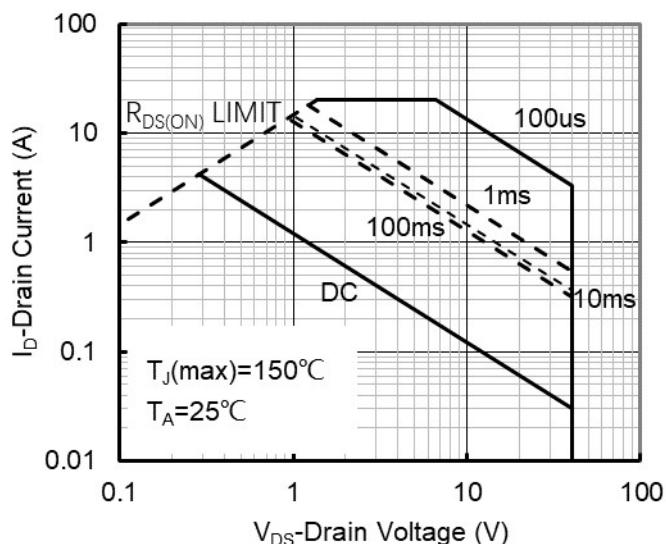


Figure 7. Safe Operation Area

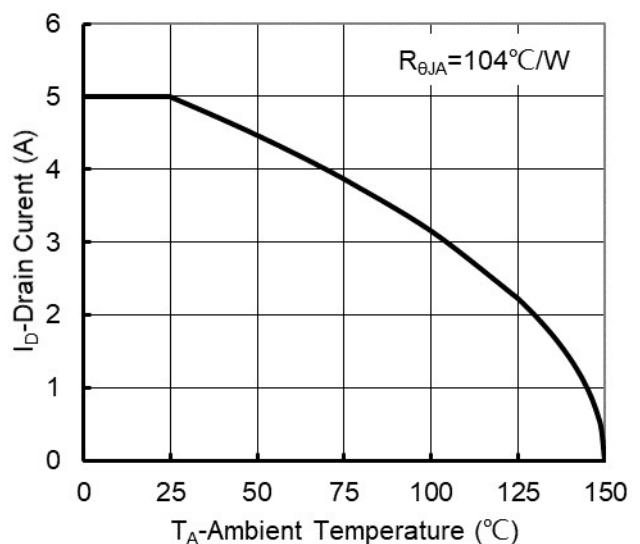


Figure 8. Maximum Continuous Drain Current vs Ambient Temperature

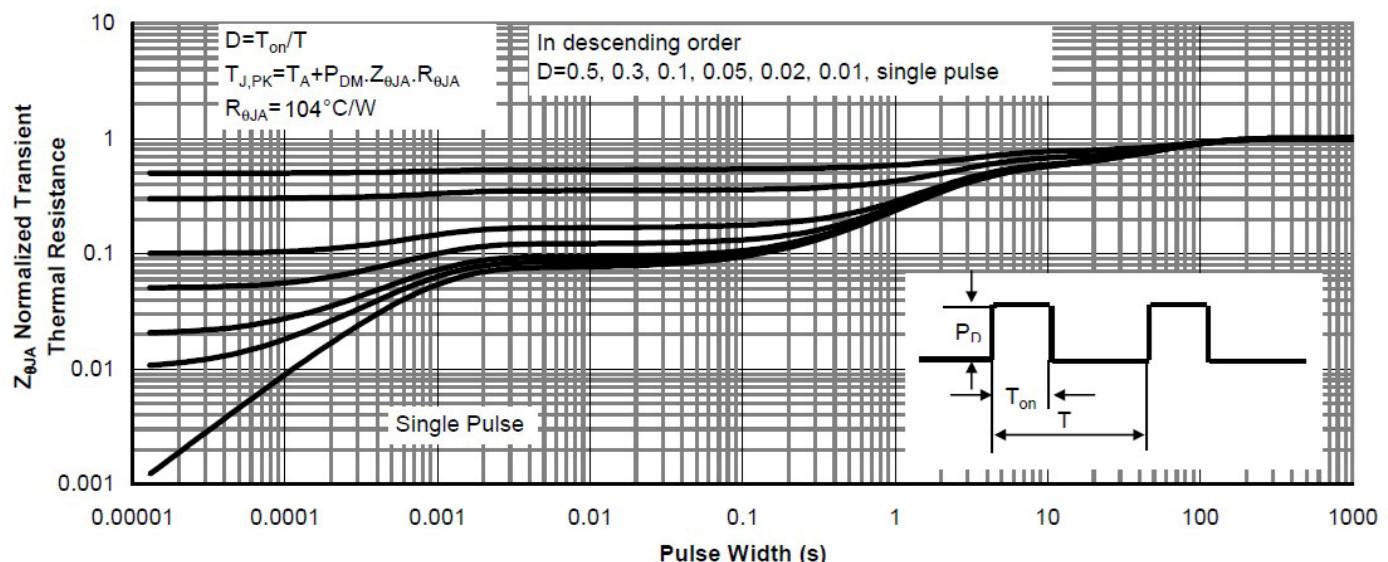
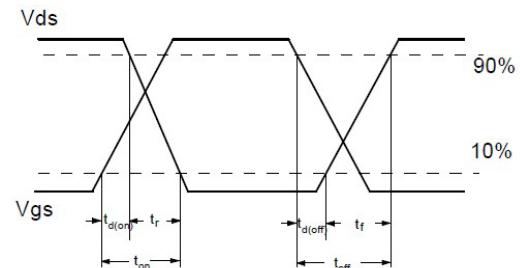
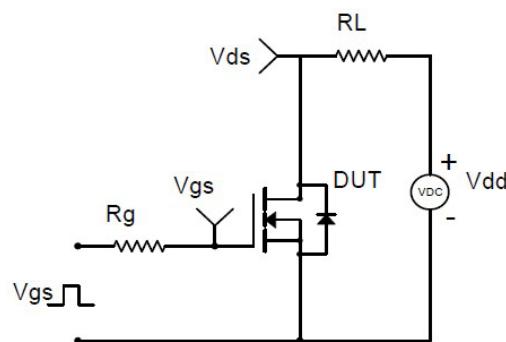
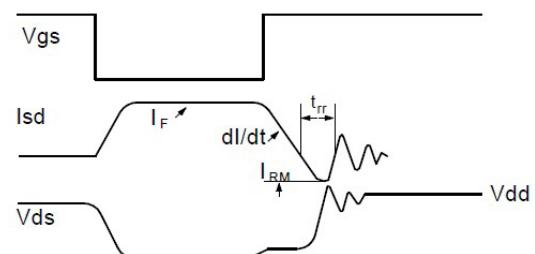
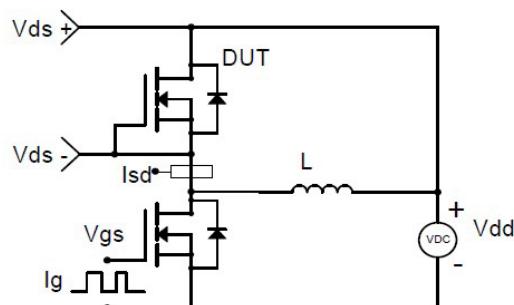


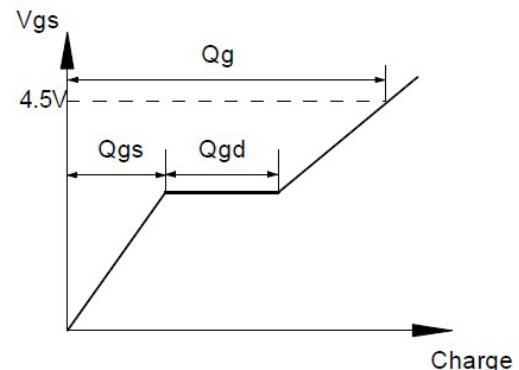
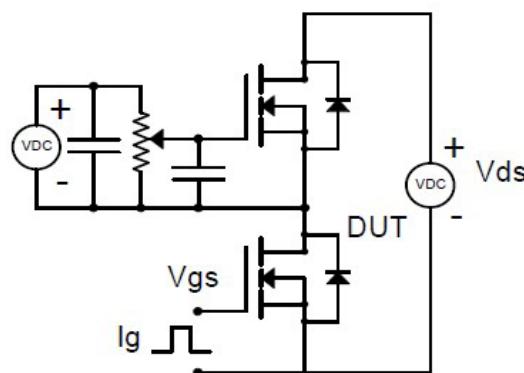
Figure 9. Normalized Maximum Transient Thermal Impedance



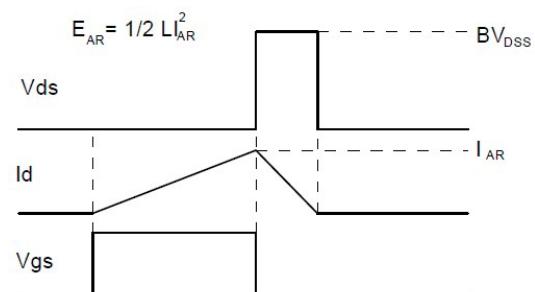
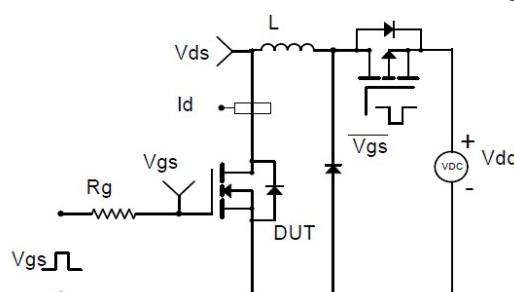
Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

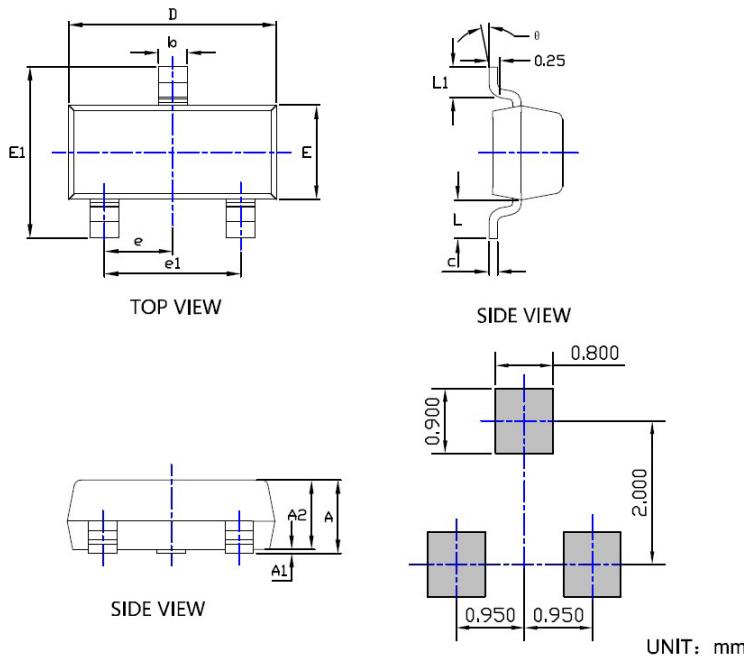


Gate Charge Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

■ SOT-23 Package information



SYMBOL	DIMENSIONS			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.035	---	0.045	0.900	---	1.150
A1	0.000	---	0.004	0.000	---	0.100
A2	0.035	0.038	0.041	0.900	0.975	1.050
b	0.012	0.016	0.020	0.300	0.400	0.500
c	0.004	---	0.008	0.100	---	0.200
D	0.110	0.114	0.118	2.800	2.900	3.000
E	0.047	0.051	0.055	1.200	1.300	1.400
E1	0.089	0.094	0.100	2.250	2.400	2.550
e	0.037TYP			0.950TYP		
e1	0.071	0.075	0.079	1.800	1.900	2.000
L	0.022REF			0.550REF		
L1	0.012	0.016	0.200	0.300	0.400	0.500
θ	0°	---	8°	0°	---	8°

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.